IN THE SPECIFICATION

Please replace the paragraph beginning at page 2, line 5 with the following rewritten paragraph:

This application is related to the following co-pending and commonly assigned patent application, which is hereby incorporated by reference herein: application Ser. No. 10/058,650, entitled "METHOD OF SEPARATING AND HANDLING A THIN SEMICONDUCTOR DIE ON A WAFER," filed on same date herewith, by Shiuh-Hui Steven Chen, Cheryl Field, Didier R. Lefebvre, and Joe Pin Wang, attorney's docket number AP01985.

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IN THE CLAIMS

Please cancel **Claims 13-20**.

Please add the following **Claims 21-28.**

21. A wafer comprising:

a support body made of a semiconductor material, the support body having a plurality of apertures and having a first thickness; and

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a plurality of semiconductor dies each semiconductor die having an integrated circuit formed thereon and having a second thickness, the second thickness being substantially less than the first thickness;

wherein each of the dies is retained within one of the apertures in the support body such that a gap exists between an outer perimeter of each die and the support body, each die retained within the aperture by a plurality of tethers that extend across the gap and between the outer perimeter of each die and the support body.

22. The wafer of claim 21 wherein at least one of the plurality of tethers is substantially triangular in shape.

23. The wafer of claim 22 wherein the at least one substantially triangular tether has a base and a tip, the base of the tether being attached to the support body of the wafer and the tip of the tether extending across the gap and attached to the die.

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24. The wafer of claim 21 wherein at least one of the plurality of tethers has a portion that extends across the gap, the portion extending across the gap having its smallest width adjacent to the outer perimeter of the die.

25. The wafer of claim 21 wherein at least one of the plurality of tethers has a portion that extends across the gap, the portion extending across the gap having at least a portion of a groove.

26. The wafer of claim 21 wherein at least one of the plurality of tethers has a portion that extends across the gap, the portion extending across the gap having at least a portion of a hole.

27. The wafer of claim 21 wherein the integrated circuit formed on the die is adapted for a pressure sensor.

28. The wafer of claim 21 wherein the plurality of tethers are made of a polyimide material.

Attached hereto as ATTACHMENT A is a mark-up version of the changes made to the specification and claims by the current amendment and response. The attached pages are captioned **"Version with Markings to Show Changes Made."**